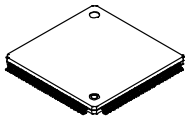
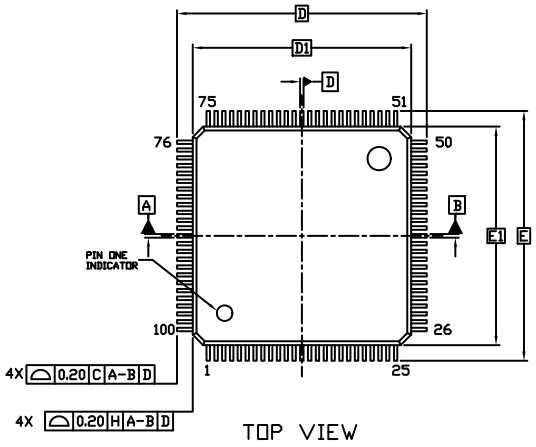
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

TQFP100 14x14, 0.5P
CASE 932BR
ISSUE O

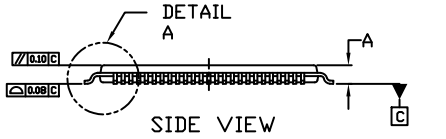
DATE 03 JUL 2018

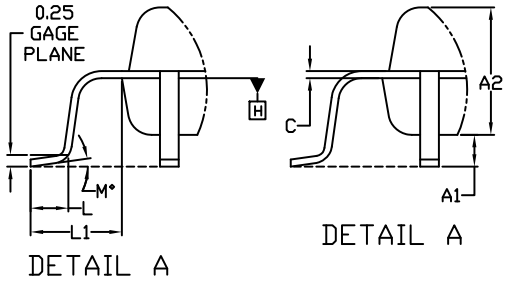


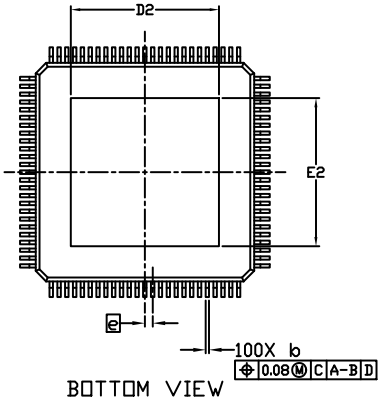


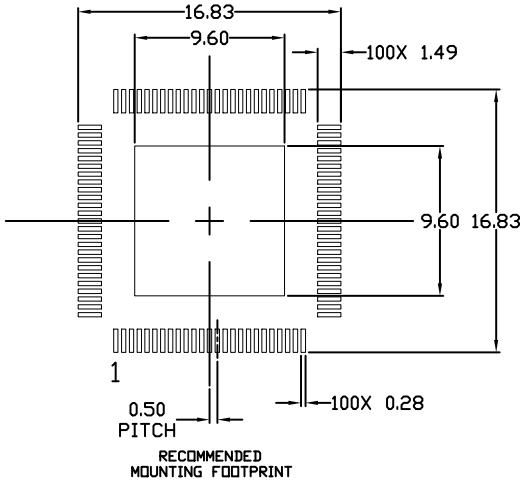
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
5. THE TOP PACKAGE BODY SIZE IS SMALLER THAN THE BOTTOM PACKAGE SIZE AND TOP PACKAGE WILL NOT OVERHANG THE BOTTOM.
6. DATUM PLANE H IS LOCATED AT THE BOTTOM MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
7. DIMENSIONS D1 AND E1 TO BE DETERMINED AT DATUM PLANE H.
8. DATUMS A-B AND D ARE DETERMINED AT DATUM PLANE H.
9. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
10. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.
11. EXPOSED PAD SIZE IS AFFECTED BY MOLD FLASH AND MOLD FLASH IS CONTROLLED BY FVI(FINAL VISUAL INSPECTION) SPEC.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	---	---	1.20
A1	0.05	---	0.15
A2	0.95	1.00	1.05
b	0.17	0.22	0.27
c		0.20 REF	
D	15.80	16.00	16.20
D1	13.80	14.00	14.20
D2		9.50 REF	
E	15.80	16.00	16.20
E1	13.80	14.00	14.20
E2		9.50 REF	
e		0.50 BSC	
L	0.45	0.60	0.75
L1		1.00 REF	
M	0°	---	7°

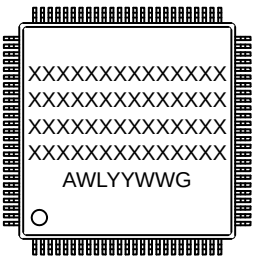








GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**TQFP100 14X14, 0.5P**	**PAGE 1 OF 1**

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